



an Open Access Journal by MDPI

BIM and GIS Integration for Driving Smarter Decisions

Guest Editors: Message from the Guest Editors Prof. Dr. Peng Wu Dear Colleagues, Dr. Wenchi Shou Dr. Junxiang Zhu Dr. Jun Wang Deadline for manuscript submissions: closed (31 December 2020)

Building information modelling (BIM) is playing a key role in improving building life cycle information management. Geographic information systems (GIS) are widely used by the geospatial industry to gather, manage and analyse heterogeneous, geolocation-based data. Recently, Smart City, Digital Twin and City Brain have been attracting a lot of attention from researchers. The core idea behind those terms is to develop 3D digital replicas of the physical world by integrating BIM and GIS. Topics in our special issue include but are not limited to:

- BIM and GIS integration for smart cities and/or communities/smart infrastructure/life cycle asset data management/better project planning, design, construction, operation and maintenance;
- Data integration/interoperability between BIM and GIS
- Semantic integration between BIM and GIS;
- Improvement of international open data standards: IFC, CityGML, InfraGML, etc.;
- Advancing BIM and GIS through Artificial Intelligence;
- BIM and GIS data visualisation;
- Web-based BIM and GIS integration;
- Other application of BIM and GIS integration.





mdpi.com/si/40973





an Open Access Journal by MDPI

Editor-in-Chief

Message from the Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions. **High Visibility:** indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases. **Journal Rank:** JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (*General Engineering*)

Contact Us

Applied Sciences Editorial Office MDPI, St. Alban-Anlage 66 4052 Basel, Switzerland Tel: +41 61 683 77 34 www.mdpi.com mdpi.com/journal/applsci applsci@mdpi.com X@Applsci